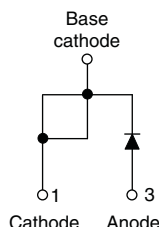


HEXFRED® Ultrafast Soft Recovery Diode, 25 A



TO-220AC



FEATURES

- Ultrafast and ultrasoft recovery
- Very low I_{RRM} and Q_{rr}
- AEC-Q101 qualified, meets JESD 201 class 2 whisker test
- Material categorization:
for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

DESCRIPTION

VS-HFA25TB60... is a state of the art ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 25 A continuous current, the VS-HFA25TB60... is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to “snap-off” during the t_b portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA25TB60... is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

PRIMARY CHARACTERISTICS

$I_{F(AV)}$	25 A
V_R	600 V
V_F at I_F	1.7 V
t_{rr} typ.	23 ns
T_J max.	150 °C
Package	TO-220AC
Circuit configuration	Single

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	V_R		600	V
Maximum continuous forward current	I_F	$T_C = 100\text{ °C}$	25	A
Single pulse forward current	I_{FSM}		225	
Maximum repetitive forward current	I_{FRM}		100	
Maximum power dissipation	P_D	$T_C = 25\text{ °C}$	125	W
		$T_C = 100\text{ °C}$	50	
Operating junction and storage temperature range	T_J, T_{Stg}		-55 to +150	°C



ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX. UNITS
Cathode to anode breakdown voltage	V _{BR}	I _R = 100 μA		600	-	- V
Maximum forward voltage	V _{FM}	I _F = 25 A	See fig. 1	-	1.3	1.7
		I _F = 50 A		-	1.5	2.0
		I _F = 25 A, T _J = 125 °C		-	1.3	1.7
Maximum reverse leakage current	I _{RM}	V _R = V _R rated	See fig. 2	-	1.5	20 μA
		T _J = 125 °C, V _R = 0.8 x V _R rated		-	600	2000
Junction capacitance	C _T	V _R = 200 V	See fig. 3	-	55	100 pF
Series inductance	L _S	Measured lead to lead 5 mm from package body		-	8.0	- nH

DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX. UNITS
Reverse recovery time See fig. 5, 6 and 16	t _{rr}	I _F = 1.0 A, dI _F /dt = 200 A/μs, V _R = 30 V		-	23	- ns
	t _{rr1}	T _J = 25 °C	I _F = 25 A dI _F /dt = 200 A/μs V _R = 200 V	-	50	-
	t _{rr2}	T _J = 125 °C		-	105	-
Peak recovery current See fig. 7 and 8	I _{RRM1}	T _J = 25 °C		-	4.5	- A
	I _{RRM2}	T _J = 125 °C		-	8.0	-
Reverse recovery charge See fig. 9 and 10	Q _{rr1}	T _J = 25 °C		-	112	- nC
	Q _{rr2}	T _J = 125 °C		-	420	-
Peak rate of fall of recovery current during t _b See fig. 11 and 12	dI _(rec) M/dt1	T _J = 25 °C		-	250	- A/μs
	dI _(rec) M/dt2	T _J = 125 °C		-	160	-

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX. UNITS
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s		-	-	300 °C
Thermal resistance, junction to case	R _{thJC}			-	-	1.0 K/W
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount		-	-	80 K/W
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased		-	0.5	-
Weight				-	2.0	- g
				-	0.07	- oz.
Mounting torque				6.0 (5.0)	-	12 (10) kgf · cm (lbf · in)
Marking device		Case style TO-220AC		HFA25TB60H		

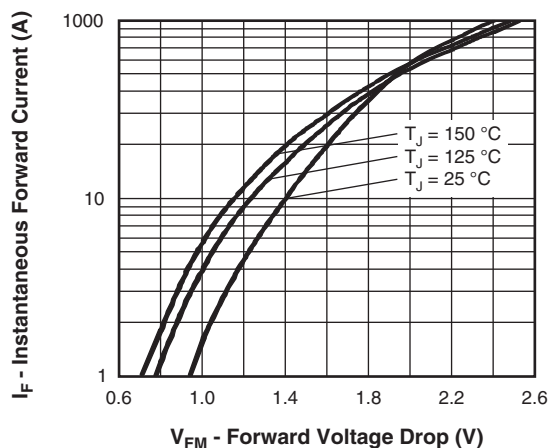


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

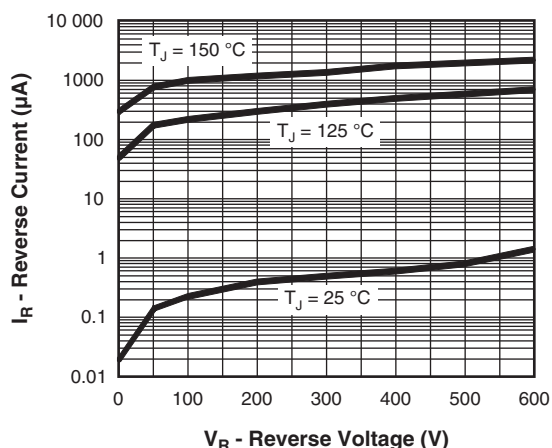


Fig. 2 - Typical Reverse Current vs. Reverse Voltage

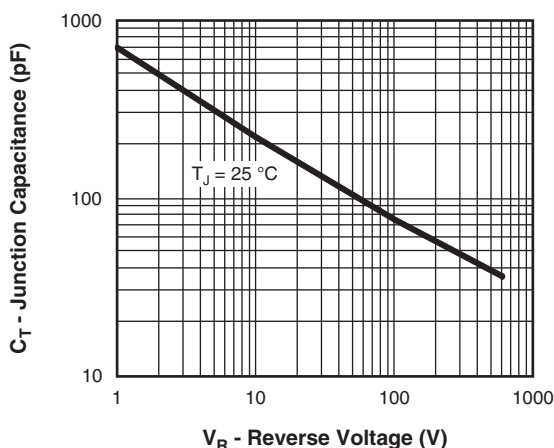


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

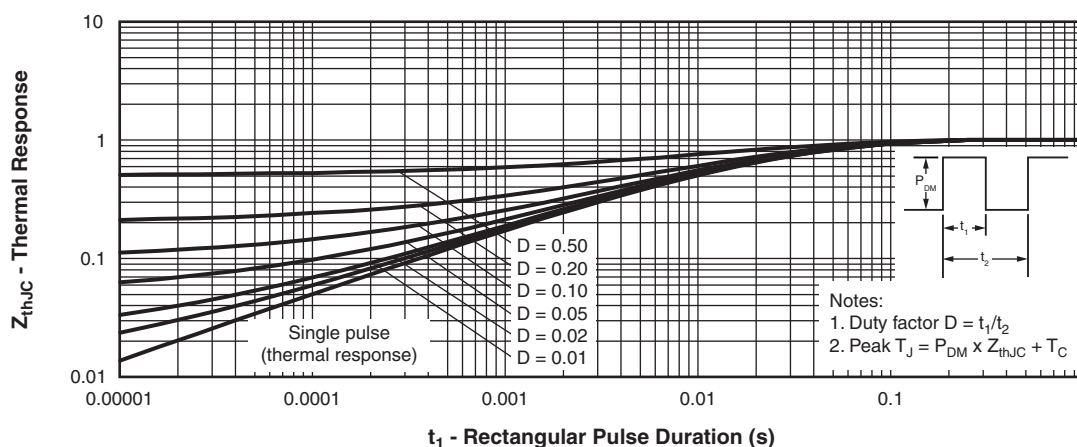
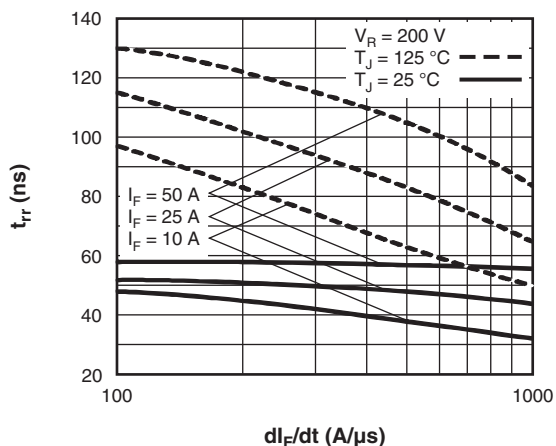
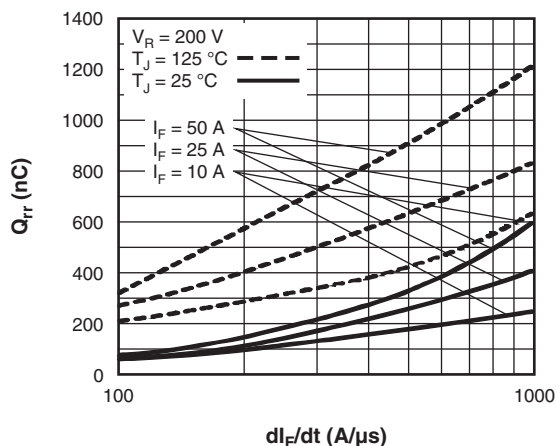
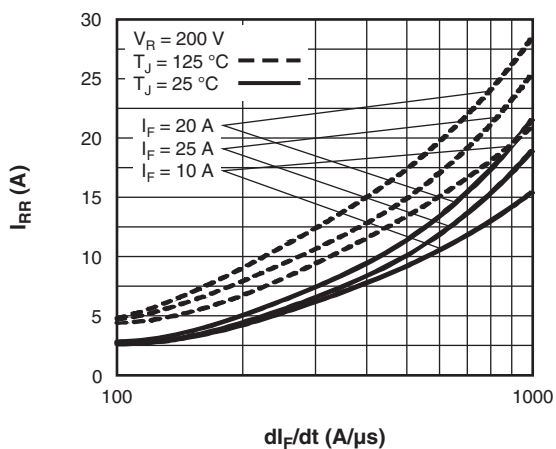
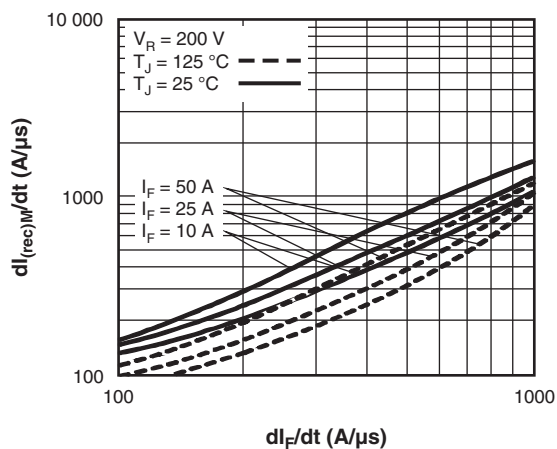


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics


Fig. 5 - Typical Reverse Recovery Time vs. di_F/dt

Fig. 7 - Typical Stored Charge vs. di_F/dt

Fig. 6 - Typical Recovery Current vs. di_F/dt

Fig. 8 - Typical $di_{(rec)M}/dt$ vs. di_F/dt

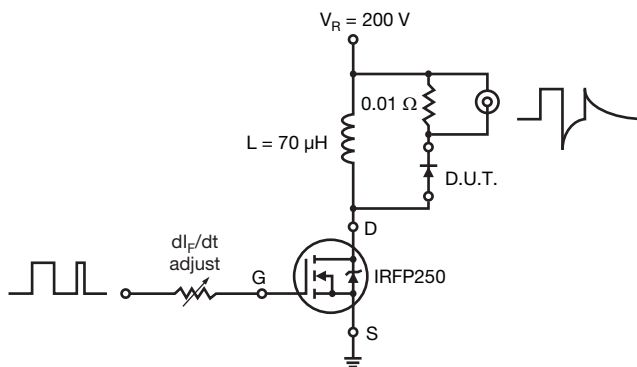


Fig. 9 - Reverse Recovery Parameter Test Circuit

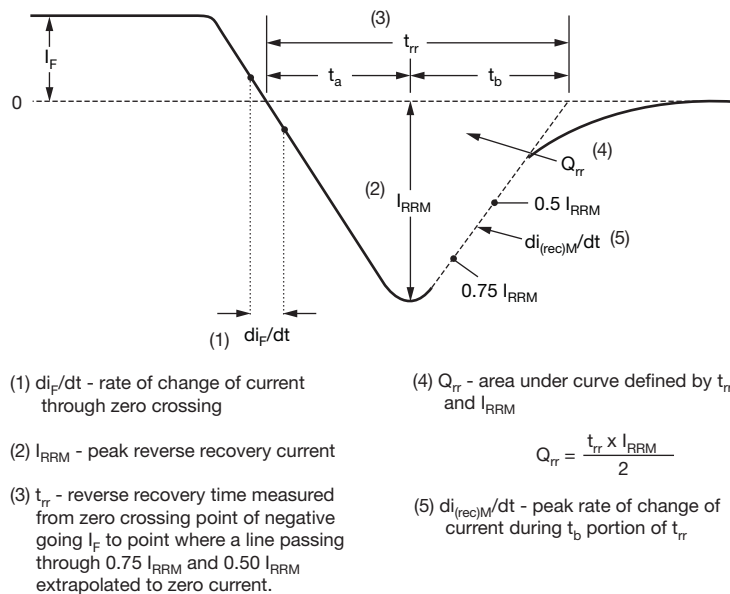


Fig. 10 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code	VS-	HF	A	25	TB	60	H	N3
	1	2	3	4	5	6	7	8

- | | | |
|---|---|--|
| 1 | - | Vishay Semiconductors product |
| 2 | - | HEXFRED® family |
| 3 | - | Electron irradiated |
| 4 | - | Current rating (25 = 25 A) |
| 5 | - | Package:
TB = TO-220AC |
| 6 | - | Voltage rating (60 = 600 V) |
| 7 | - | H = AEC-Q101 qualified |
| 8 | - | Environmental digit:
-N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free |

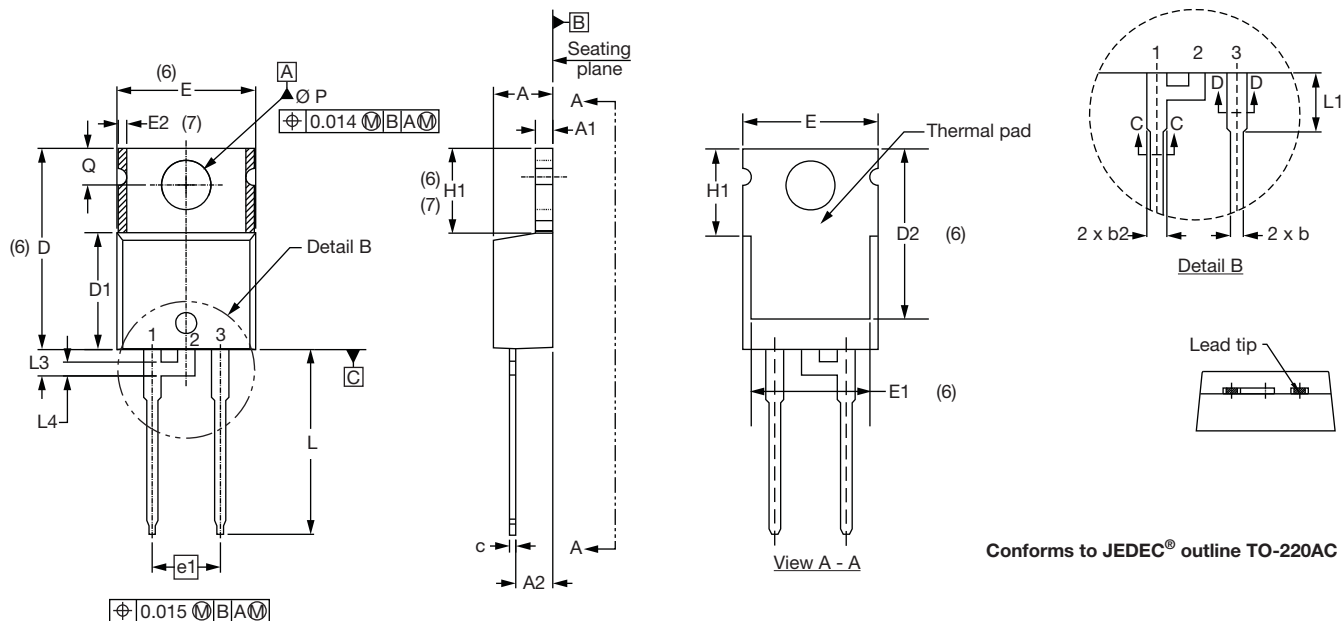
ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-HFA25TB60HN3	50	1000	Antistatic plastic tube

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95221
Part marking information	www.vishay.com/doc?95068
SPIICE model	www.vishay.com/doc?95546



TO-220AC

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.25	4.65	0.167	0.183	
A1	1.14	1.40	0.045	0.055	
A2	2.56	2.92	0.101	0.115	
b	0.69	1.01	0.027	0.040	
b1	0.38	0.97	0.015	0.038	4
b2	1.20	1.73	0.047	0.068	
b3	1.14	1.73	0.045	0.068	4
c	0.36	0.61	0.014	0.024	
c1	0.36	0.56	0.014	0.022	4
D	14.85	15.25	0.585	0.600	3
D1	8.38	9.02	0.330	0.355	
D2	11.68	12.88	0.460	0.507	6
E	10.11	10.51	0.398	0.414	3, 6

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
E1	6.86	8.89	0.270	0.350	6
E2	-	0.76	-	0.030	7
e1	4.88	5.28	0.192	0.208	
H1	5.84	6.86	0.230	0.270	6, 7
L	13.52	14.02	0.532	0.552	
L1	3.32	3.82	0.131	0.150	2
L3	1.78	2.13	0.070	0.084	
L4	0.76	1.27	0.030	0.050	2
Ø P	3.54	3.73	0.139	0.147	
Q	2.60	3.00	0.102	0.118	

Notes

- Dimensioning and tolerancing as per ASME Y14.5M-1994
- Lead dimension and finish uncontrolled in L1
- Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- Dimension b1, b3 and c1 apply to base metal only
- Controlling dimension: inches
- Thermal pad contour optional within dimensions E, H1, D2 and E1
- Dimension E2 x H1 define a zone where stamping and singulation irregularities are allowed
- Outline conforms to JEDEC TO-220, D2 (minimum) where dimensions are derived from the actual package outline



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